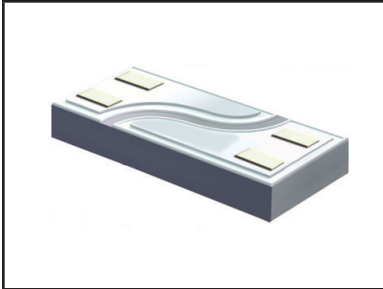


250W UNBUMPED FLIP CHIP TVS ARRAY



U0402 PACKAGE

DESCRIPTION

The U0402FCxxC Series Flip Chips employ advanced silicon P/N junction technology for unmatched board-level transient voltage protection against Electrostatic Discharge (ESD) and Electrical Fast Transients (EFT). Developed specifically for high-density circuit protection, this series meets the IEC 61000-4-2 and 61000-4-4 requirements. These devices are ideally suited for handheld devices, PCMCIA and SMART cards.

This series provides ESD protection greater than 25 kilovolts with a peak pulse power dissipation of 250 Watts per line for an 8/20 μ s waveform. In addition, the U0402FCxxC series features superior clamping performance, low leakage current characteristics and a response time of less than a nanosecond. Their low inductance virtually eliminates overshoot voltage due to package inductance.

FEATURES

- Compatible with IEC 61000-4-2 (ESD): Air 15kV, Contact 8kV
- Compatible with IEC 61000-4-4 (EFT): 40A, 5/50ns
- ESD Protection > 25 kilovolts
- Available in Voltages Ranging from 3.3V to 36V
- 250 Watts Peak Pulse Power per Line (tp = 8/20 μ s)
- Bidirectional Configuration and Monolithic Structure
- Protection for 1 Line
- RoHS Compliant
- REACH Compliant

APPLICATIONS

- Cellular Phones
- MCM Boards
- Wireless Communication Circuits
- IR LEDs
- SMART & PCMCIA Cards

MECHANICAL CHARACTERISTICS

- Standard EIA Chip Size: 0402
- Approximate Weight: 0.73 milligrams
- Lead-Free Plating
- Solder Reflow Temperature:
 - Lead-Free - Sn/Ag/Cu, 96/3.5/0.5: 260-270°C
- Flammability Rating UL 94V-0
- 8mm Plastic Tape per EIA Standard 481

PIN CONFIGURATION



TYPICAL DEVICE CHARACTERISTICS
MAXIMUM RATINGS @ 25°C Unless Otherwise Specified

PARAMETER	SYMBOL	VALUE	UNITS
Peak Pulse Power (tp = 8/20μs) - See Figure 1	P _{PP}	250	Watts
Operating Temperature	T _A	-55 to 150	°C
Storage Temperature	T _{STG}	-55 to 150	°C

ELECTRICAL CHARACTERISTICS PER LINE @ 25°C Unless Otherwise Specified

PART NUMBER (Note 1)	RATED STAND-OFF VOLTAGE V _{WM} VOLTS	MINIMUM BREAKDOWN VOLTAGE @ 1mA V _(BR) VOLTS	MAXIMUM CLAMPING VOLTAGE (Fig. 2) @ I _p = 1A V _c VOLTS	MAXIMUM CLAMPING VOLTAGE (Fig. 2) @ 8/20μS V _c @ I _{PP}	MAXIMUM LEAKAGE CURRENT (Note 2) @ V _{WM} I _D μA	TYPICAL CAPACITANCE @ 0V, 1MHz C pF
U0402FC3.3C	3.3	4.0	7.0	12.5V @ 20A	75*	150
U0402FC05C	5.0	6.0	9.8	14.7V @ 17A	10**	100
U0402FC08C	8.0	8.5	13.4	19.2V @ 13A	10***	75
U0402FC12C	12.0	13.3	19.0	29.7V @ 9A	1	50
U0402FC15C	15.0	16.7	24.0	35.7V @ 7A	1	40
U0402FC24C	24.0	26.7	43.0	55.0V @ 5A	1	30
U0402FC36C	36.0	40.0	64.0	84.0V @ 3A	1	25

NOTES

- All devices are bidirectional. Electrical characteristics apply in both directions.
- *Maximum leakage current < 5μA @ 2.8V. **Maximum leakage current < 500nA @ 3.3V. ***Maximum leakage current < 200nA @ 5V.

TYPICAL DEVICE CHARACTERISTICS

FIGURE 1
PEAK PULSE POWER VS PULSE TIME

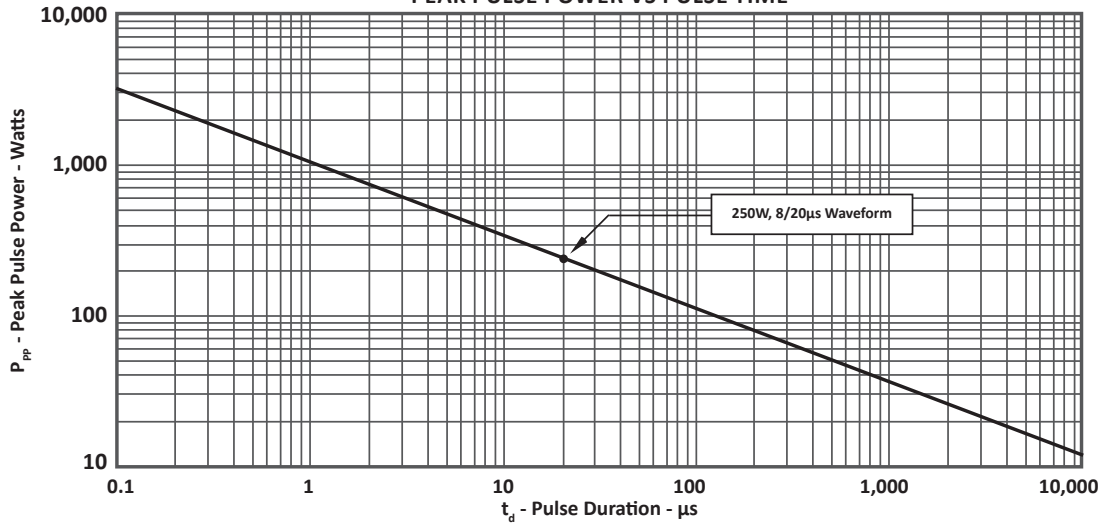


FIGURE 2
PULSE WAVE FORM

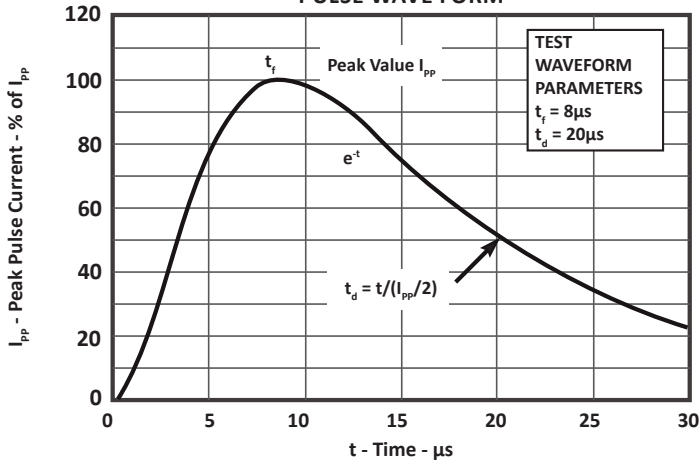
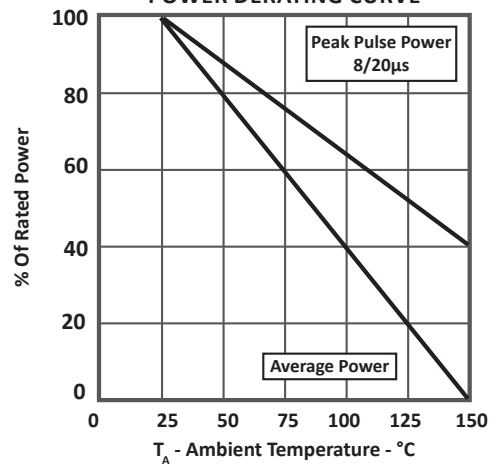


FIGURE 3
POWER DERATING CURVE



TYPICAL DEVICE CHARACTERISTICS

FIGURE 4
OVERSHOOT & CLAMPING VOLTAGE FOR U0402FC05C

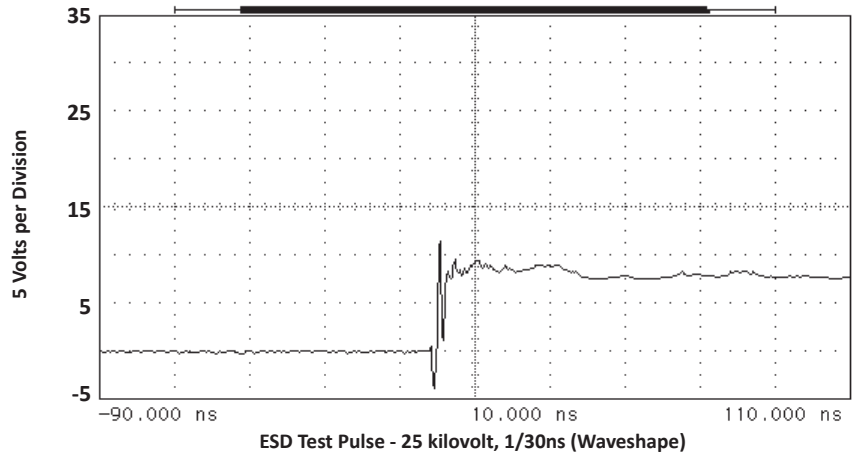
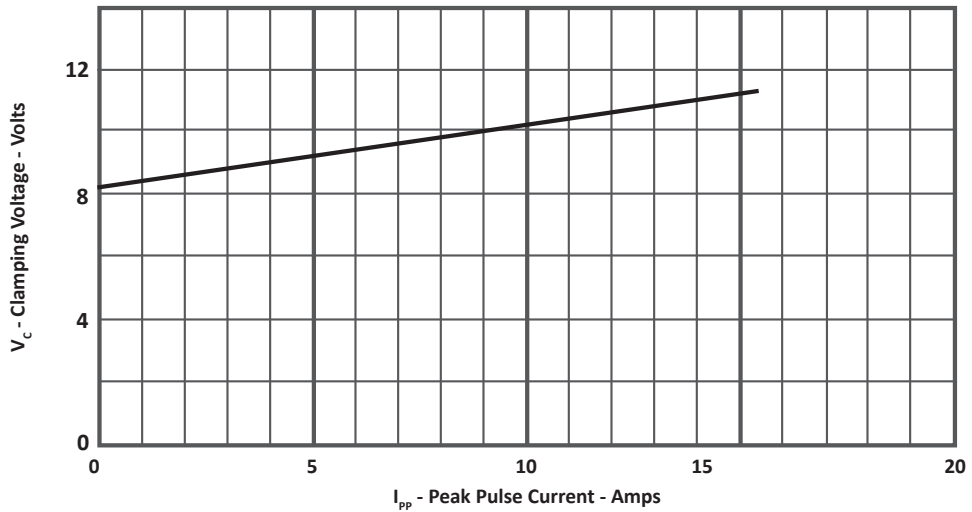


FIGURE 5
TYPICAL CLAMPING VOLTAGE VS PEAK PULSE CURRENT U0402FC05C



SOLDER REFLOW INFORMATION

PRINTED CIRCUIT BOARD RECOMMENDATIONS	
PARAMETER	VALUE
Pad Size on PCB	0.275mm
Pad Shape	Round
Pad Definition	Non-Solder Mask Defined Pads
Solder Mask Opening	0.325mm Round
Solder Stencil Thickness	0.150mm
Solder Stencil Aperture Opening (Laser cut, 5% tapered walls)	0.330mm Round
Solder Paste Type	No Clean
Pad Protective Finish	OSP (Entek Cu Plus 106A)
Tolerance - Edge To Corner Ball	±50µm
Solder Ball Side Coplanarity (Only applies to bumped devices)	±20µm
Maximum Dwell Time Above Liquidous (183°C)	60 seconds
Soldering Maximum Temperature	270°C

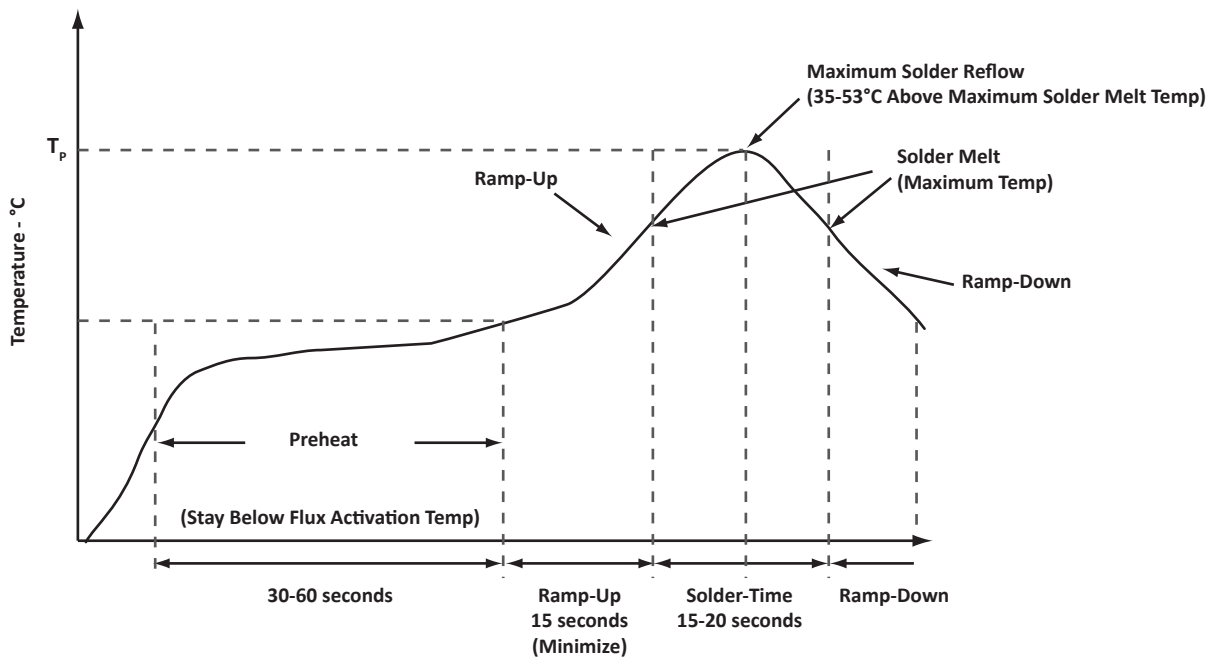
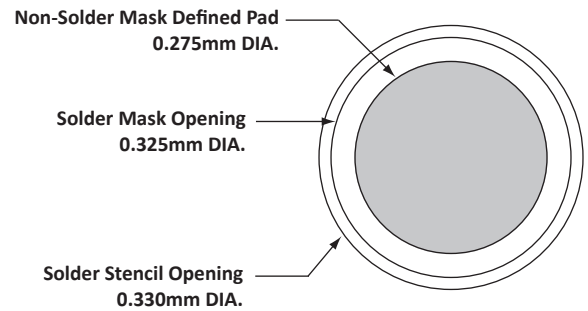
REQUIREMENTS

Temperature:

T_p for Lead-Free (Sn/Ag/Cu): 260-270°C

Preheat time and temperature depends on solder paste and flux activation temperature, component size, weight, surface area and plating.

RECOMMENDED NON-SOLDER MASK DEFINED PAD ILLUSTRATION

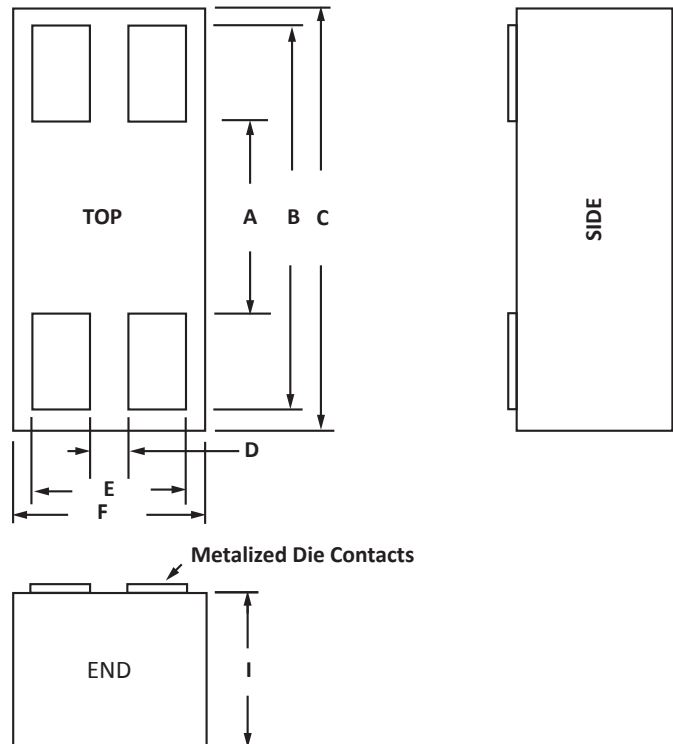


U0402 PACKAGE INFORMATION
OUTLINE DIMENSIONS

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.61		0.024	
B	0.86		0.034	
C	0.98	1.02	0.038	0.040
D	0.10		0.004	
E	0.35		0.014	
F	0.458	0.508	0.018	0.020
I	0.406		0.016	

NOTES

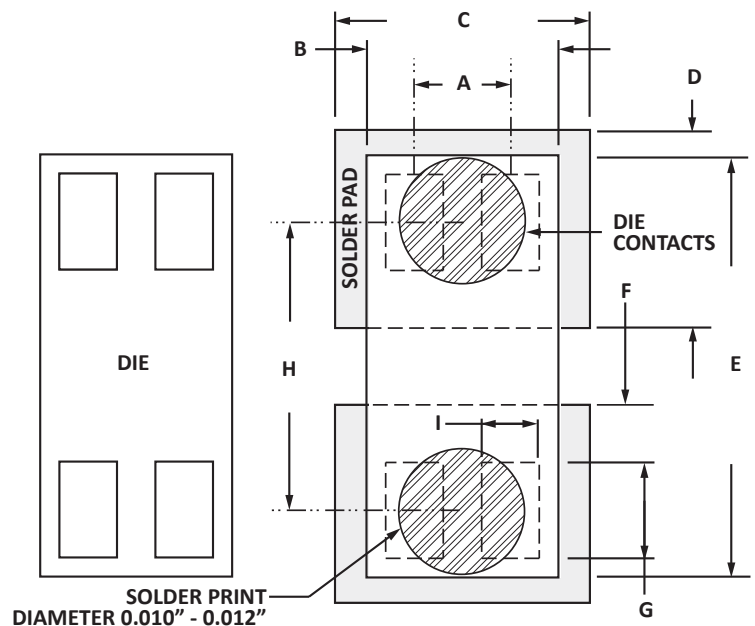
- Controlling dimensions in inches.
- Decimal tolerance: .xxx ± 0.05mm (0.002").
- Maximum chip size: 1.02mm (0.040") by 0.51mm (0.020").

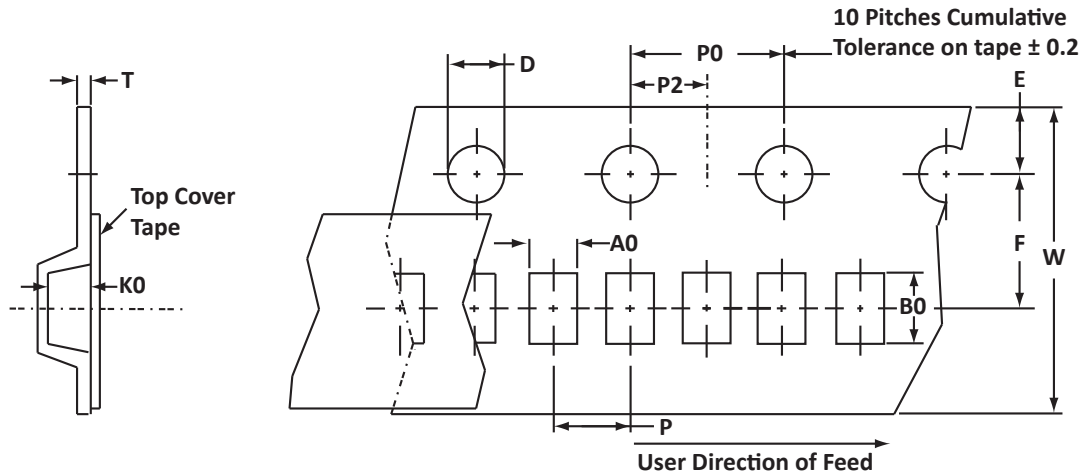

LAYOUT DIMENSIONS

DIM	MILLIMETERS		INCHES	
	NOMINAL		NOMINAL	
A	0.23		0.009	
B	0.48		0.019	
C	0.69		0.027	
D	0.46		0.018	
E	0.99		0.039	
F	0.20		0.008	
G	0.20		0.008	
H	0.66		0.026	
I	0.13		0.005	

NOTES

- Controlling dimensions in inches.
- Decimal tolerance: .xxx ± 0.05mm (0.002").

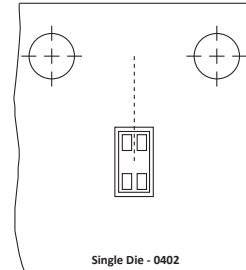


TAPE AND REEL INFORMATION

SPECIFICATIONS

REEL DIA.	TAPE WIDTH	A0	B0	K0	D	E	F	W	P0	P2	P	Tmax
178(7")	8	0.70 ± 0.05	1.15 ± 0.10	0.56 ± 0.05	1.55 ± 0.05	1.75 ± 0.10	3.50 ± 0.05	8.00 ± 0.20	4.00 ± 0.05	2.00 ± 0.05	2.00 ± 0.05	0.25

NOTES

- Dimensions in millimeters.
- Top view of tape. Metal contacts are face down in tape package.
- Orientation: preferred stencil - 0.1mm (0.004").
- Surface mount product is taped and reeled in accordance with EIA 481.
- 8mm plastic tape: 7" Reels - 5,000 (pocket under hole skipped) pieces per reel.
- Marking on Reel - part number, date code and lot number.

TAPE & REEL ORIENTATION


Package outline, pad layout and tape specifications per document number 06020.R6 8/12.

ORDERING INFORMATION

BASE PART NUMBER (xx = Voltage)	LEADFREE SUFFIX	TAPE SUFFIX	QTY/REEL	REEL SIZE	TUBE QTY
U0402FCxxC	-LF	-T75-1	5,000	7"	n/a

This device is only available in a Lead-Free configuration.

COMPANY INFORMATION

COMPANY PROFILE

In business more than 20 years, ProTek Devices™ is a privately-held company located in Tempe, Arizona, that offers a product line of transient voltage suppressors (TVS); avalanche breakdown diodes; steering diode TVS arrays and other surge suppressor component products. These TVS devices protect electronic systems from the effects of lightning, electrostatic discharge (ESD), nuclear electromagnetic pulses (NEMP), inductive switching and EMI / RFI. ProTek Devices also offers high performance interface and linear products that include analog switches; multiplexers; LED drivers; audio control ICs; RF and related high frequency products. The analog devices work in a host of consumer; industrial; automotive and other applications.

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PATENT INFORMATION: This device is patented under U.S. Patent No. Des. "D456,367S".